



I&C Taiwan TC Chapter

Meeting Summary and Minutes

Taiwan Summer Standards Meeting 2018

Friday, September 7, 2018, 14:00 – 16:00

Hsinchu Ambassador Hotel 13F Meeting Room C, 188 Chung Hua Road, Section 2, Hsinchu, Taiwan

TC Chapter Announcements

Next TC Chapter Meeting

March, 2019 (Tentative)

SEMI Taiwan Office, Hsinchu, Taiwan

Table 1 Meeting Attendees

Deputy Co-Chairs: Robert Chien (TSMC)

SEMI Staff: Dean Chang

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
TSMC	Liao	Robin	TSMC	Chen	Ivan
Gallant Precision Machining	Hsiao	Stone	Edwards	Lee	Nien Ting
MUST	Jan	Sen-Ren	Facet	Chang	Robin
ASE	Chang	Kuan Fu	Willis Towers Watson	Wu	Bright
Cimetrix	Lee	Michael	Flagship International	Huang	Jack

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
Fab and Equipment Information Security Task Force	None.	Paxson Yang (TSMC)

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None.	Fab and Equipment Information Security Task Force

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.



Table 5 Activities Approved by the GCS between meetings of the TC Chapter

#	Type	SC/TF/WG	Details
None			

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	When	TF	Details
None			

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
6147	Backend Factory Integration TF	New Standard: Specification of Backend Die Traceability	2019/12/07

Table 9 SNARF(s) Abolished

#	TF	Title
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 11 New Action Items

Item #	Assigned to	Details
1	Dean Chang	I&C TC meeting will be held twice a year: March at SEMI Taiwan Office. September at Hsinchu Ambassador Hotel. (In conjunction with E-Manufacturing & Design Collaboration Symposium)
2	Paxson Yang	Propose to form a new Task Force: Fab and Equipment Information Security Task Force

Table 12 Previous Meeting Action Items

Item #	Assigned to	Details
1	Dean Chang	SEMI Taiwan will hold a Smart Manufacturing and Risk Management for High Tech Manufacturing Seminar on May 28, 2018 at Hsinchu.(Completed)

1 Welcome, Reminders, and Introductions

Committee deputy Co-Chairs: Iven Chen (TSMC) called the meeting to order at 15:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Meeting Reminder_2018

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve previous meeting minute

By / 2nd: Jack Huang (Flagship International) / Michael Lee (Cimetrix)

Discussion: After review, all TC members agreed to approve it

Vote: 10-0 in favor. Motion passed

Attachment: 20180323_I&C Meeting Minutes

3 Liaison Reports

3.1 I&C North America TC Chapter

3.1.1 Dean Chang (SEMI TW) reported for the I&C North America TC Chapter. Of note:

Action Item:

- Ballot Results Cycle 5-2018
 - Passed as ballot:
 - Doc 6378: Line-item Revision to SEMI E133, Specification for Automated Process Control Systems Interface and E133.1 Specification for XML messaging for Process Control Systems (PCS)
 - Doc 6333: Line-item Revision to SEMI E54.23-0513, Specification for Sensor/Actuator Network Communications for CC-Link IE Field Network
 - Doc 6335: Line-Item Revision to SEMI E134, Specification for Data Collection Management
 - Doc 6386: Reapproval to SEMI E90-0312, Specification for Substrate Tracking
 - Doc6381: Line-item Revision to SEMI E40-0813, Standard for Processing Management, to correct nonconforming title
 - Doc6382: Line-item Revision to SEMI E40.1-0813, SECS-II Support for Processing Management Standard, to correct nonconforming title
 - Doc6379: Line-item Revision to SEMI E39-0703, Object Services Standard: Concepts, Behavior, And Services, to correct nonconforming title
 - Doc6380: Line-item Revision to SEMI E39.1-0703, SECS-II Protocol for Object Services Standard (OSS), to correct nonconforming title
 - Failed:
 - Doc6335: Line-Item Revision to SEMI E134, Specification for Data Collection Management



- Doc6336A: Line-Item Revision to SEMI E138, Specification for XML Semiconductor Common Components
- Doc6337A: Line Item Revision to SEMI E132, Specification for Client Authentication and Authorization
- Doc6348: Revision to SEMI E30, Specification for the Generic Model For Communications and Control of Manufacturing Equipment (GEM)
- Doc6349: Revision to E37.1, High-Speed SECS Message Services Single Selected-Session Mode (HSMS-SS OR HSMS-SSS)
- Doc6114B: Line-item Revision to SEMI E5-0813, *SEMI Equipment Communications Standard 2 Message Content (SECS-II)*

- Next TC Meeting will be held on November 7, 2018 at SEMI Headquarters, Milpitas California.

Attachment: NA I&C Liaison Report July 2018_v1

3.2 I&C Japan TC Chapter

3.2.1 Dean Chang (SEMI TW) reported for the I&C Japan TC Chapter. Of note:

Action Item:

- Leadership Changes:
 - Sensor Bus TF: added H. Miura (Techno-Holon) to be a new leader
- Ballot Results:
 - Passed
 - Line Item 1: Adding reference and mapping about E54.22 ‘Specification for Sensor/Actuator Network Specific Device Model for Vacuum Pressure Gauge’ to proper sections of E54.21
 - Line Item 1: Adding reference and mapping about E54.22 ‘Specification for Sensor/Actuator Network Specific Device Model for Vacuum Pressure Gauge’ to proper sections of E54.12
- Next TC Meeting will be held on October 24, 2018 at SEMI Japan Office, Tokyo, Japan.

Attachment: 20180904_JA_IC_LiaisonReport_v1.0

3.3 I&C Korea TC Chapter

3.3.1 Dean Chang (SEMI TW) reported for the I&C Korea TC Chapter. Of note:

Action Item:

- Authorized Ballots
 - Doc4946E: Revision to E87 and E87.1: Adding Carrier Ready to Unload Prediction Feature
 - Doc5832B: New Standard, Specification for Equipment Generic Counter Model
 - Doc6301A: Line Item Revision to E142-0211(Reapproved 1016) Specification for Substrate Mapping: Adding packaging raw materials traceability method
- Next TC Meeting will be held on October 19, 2018 at SEMI Korea Office, Seoul, Korea.

Attachment: I&C_KR_July2018

3.4 I&C Europe TC Chapter

None.

4 SEMI Staff Report

Dean Chang (SEMI TW) gave the SEMI Staff Report. Of note:

- Document Number: 6092
 - SNARF for: New Standard: Specification for Centralized User Authentication and Role Authorization Management (CUARAM).
- 3D P&I TC members would like to invite I&C TC/Backend factory integration TF members to join 3D P&I TC meeting to discuss Die traceability issue.
- Standards Summit and Standards Members Annual Appreciation Dinner will be held at Hsinchu Ambassador hotel on December 7.
- SEMI EHS STEP Training
 - Date/time: Sept. 28th, 2018 / 13:00-17:00
 - Venue: Meeting room 201, Tainan Science Park (2F, No. 26, Nanke 3rd Road, Tainan Science Park)

Attachment: I&C TC Staff Report_20180907

5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

None

6 Task Force Reports

6.1 GEM300 Task Force

- No Activity.

6.2 Equipment Information Integration Task Force

- No Activity.
- Will modify the scope and charter in the next TC meeting.

6.3 Backend Factory Integration TF

- Continue draft Doc6147 “New Standard: Specification of Backend Die Traceability”
- TF Meeting (Monthly meeting by Con-call) :
 - 5/4 14:00~15:00
 - 6/22 14:00~15:00
 - 7/27 14:00~15:00
 - Next meeting : TBD



- Propose to postpone draft Doc6147 for one year.

Motion: Approve postpone draft Doc6147 for one year
By / 2nd: Ivan Chen (TSMC) / Jack Huang (Flagship International)
Discussion: After discuss, TC members agreed to approve it
Vote: 8-0 in favor. Motion passed

7 Old Business

- SEMI Taiwan will hold a Smart Manufacturing and Risk Management for High Tech Manufacturing Seminar on May 28, 2018 at Hsinchu.(Completed)

8 New Business

- **I&C TC meeting will be held twice a year:**
 - **March at SEMI Taiwan Office.**
 - **September at Hsinchu Ambassador Hotel. (In conjunction with E-Manufacturing & Design Collaboration Symposium)**
- Propose to form a new Task Force: Fab and Equipment Information Security Task Force.

Motion: Approve new Task Force
By / 2nd: Michael Lee (Cimetrix) / Filo Chang (ASE)
Discussion: After discuss, all TC members agreed to approve it
Vote: 10-0 in favor. Motion passed

Attachment: TFOF_Fab & Equipment Information Security Task Force

9 Next Meeting and Adjournment

The next meeting is scheduled in March 2019 (tentative), in SEMI Taiwan Office in Hsinchu. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment was at 17:00.

Respectfully submitted by:

Dean Chang
 Senior Executive Consultant
 SEMI Taiwan
 Phone: 886-3-560-1777 #801
 Email: dchang@semi.org

Minutes tentatively approved by:

Robert Chien (TSMC), Co-chair	2018/10/22
<Name> (<Company>), Co-chair	<Date approved>



Table 13 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
1_ Meeting Reminder_2018	3.3_ I&C_KR_July2018
2_20180323_I&C Meeting Minutes	3.5_ I&C TC Staff Report_20180907
3.1_ NA I&C Liaison Report July 2018_v1	7_ TFOF_Fab & Equipment Information Security Task Force
3.2_20180904_JA_IC_LiaisonReport_v1.0	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.